

md  
4-26-99

To: Honorable Commissioner o



101030198

Please record the attach

JC135 U.S. PTO  
09/29/97  
04/26/99

1. Name of conveying party(ies)

- a) Min-Chih Hsuan
- b) Cheng-Te Lin

2. Name and address of receiving party(ies):

- a) Name: United Microelectronics Corp.
- Address: No. 3, Li-Hsin Rd. II  
Science-Based Industrial Park  
Hsinchu, Taiwan  
R.O.C.

3. Nature of conveyance

- |                                     |                    |                          |                   |
|-------------------------------------|--------------------|--------------------------|-------------------|
| <input checked="" type="checkbox"/> | Assignment         | <input type="checkbox"/> | Merger            |
| <input type="checkbox"/>            | Security Agreement | <input type="checkbox"/> | Change of Name    |
| <input type="checkbox"/>            | Other _____        | <input type="checkbox"/> | License Agreement |

Execution Date: March 31, 1999 and April 1, 1999

4. Application Number(s) or Patent Number(s): Not yet assigned

The title of the (new) application is: 09/299706

WAFER LEVEL PACKAGE

5. Please send all correspondence concerning this (these) documents to:

HICKMAN STEPHENS & COLEMAN, LLP  
 P.O. Box 52037  
 Palo Alto, CA 94303-0746  
 Tel. No.: (650) 470-7430  
 Fax No.: (650) 470-7440

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- Enclosed
- Authorized to be charged to Deposit Account No. 50-0384  
(Order No. \_\_\_\_\_)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: April 26, 1999

L. Keith Stephens  
 Registration No. 32,632

05/03/1999 KHARLING 00000055 09299706  
 ( 40.00 DP )  
 03 FC:501

# ASSIGNMENT

WHEREAS,

1. Min-Chih Hsuan

2. Cheng-Te Lin

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **WAFER LEVEL PACKAGE**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp.

of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

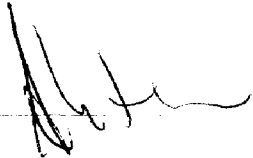
hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

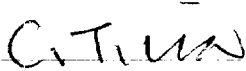
Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

# ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature:   
Sole or First Joint Inventor: Min-Chih Hsuan

Date: 1999-4-1

Signature:   
Second Joint Inventor (if any): Cheng-Te Lin

Date: 1999-3-31